



## CERAMIC BALUN

# RF Transformer

# NCS1-332+

50Ω 700 to 3300 MHz 1:1 Ratio

### FEATURES

- Wideband, 700 to 3300 MHz
- Low insertion loss, 1.0 dB
- Tiny size 0805
- LTCC construction
- Low cost



Generic photo used for illustration purposes only

CASE STYLE: GE0805C-9

### APPLICATIONS

- LTE
- WLAN
- ISM
- WiFi

#### +RoHS Compliant

The +Suffix identifies RoHS Compliance. See our web site for RoHS Compliance methodologies and qualifications

### ELECTRICAL SPECIFICATIONS AT 25°C

Parameter	Frequency (MHz)	Min.	Typ.	Max.	Units
Impedance Ratio			1		
Frequency Range		700		3300	MHz
Insertion Loss <sup>1</sup> (average)	700 - 3300	—	0.9	1.8	dB
	1500 - 2700	—	0.7	—	
Amplitude Unbalance	700 - 3300	—	0.5	1.5	dB
	1500 - 2700	—	0.2	—	
Phase Unbalance <sup>2</sup>	700 - 3300	—	8	15	Degree
	1500 - 2700	—	7	—	
Input Return Loss	700 - 3300	—	13	—	dB
	1500 - 2700	—	18	—	

1. Reference Demo Board TB-910+ with auto port extension and impedance conversion at secondary and secondary dot.

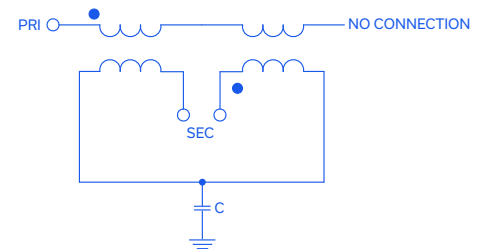
2. Relative to 180°

### MAXIMUM RATINGS

Parameter	Ratings
Operating Temperature	-40°C to 85°C
Storage Temperature	-55°C to 100°C
RF Power <sup>3</sup>	3W at 25°C

3. Passband rating, derate linearly to 1W at 100°C ambient  
Permanent damage may occur if any of these limits are exceeded.

### CONFIGURATION R



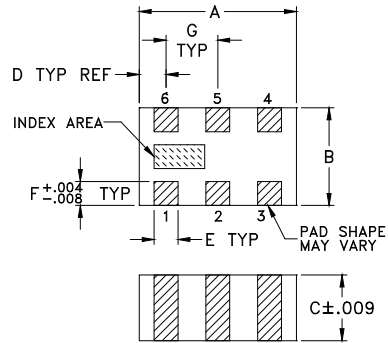


### PAD CONNECTIONS

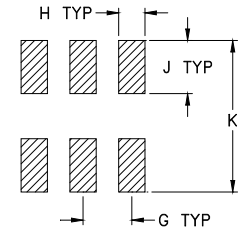
PRIMARY DOT (Unbalanced Port)	1
GND or DC feed + RF GND	2
SECONDARY DOT (Balanced)	3
SECONDARY (Balanced)	4
NO CONNECTION	6
GND	5

PRODUCT MARKING: N/A

### OUTLINE DRAWING

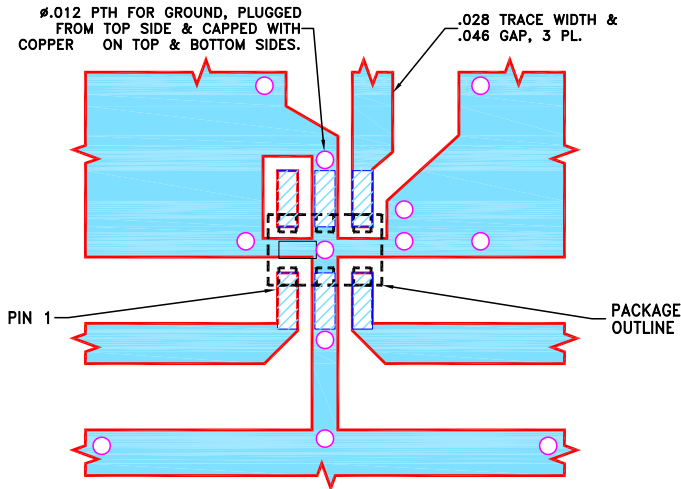


### PCB Land Pattern



Suggested Layout,  
Tolerance to be within ±.002

### DEMO BOARD MCL P/N: TB-910+ SUGGESTED PCB LAYOUT (PL-583)



**NOTES:**

- TRACE WIDTH & GAP PARAMETERS ARE SHOWN FOR FR4, GRADE IT-180TC (ITEQ CORP.); DIELECTRIC THICKNESS: .016±.0015; COPPER: 1/2 OZ. EACH SIDE. FOR OTHER MATERIALS TRACE WIDTH AND GAP MAY NEED TO BE MODIFIED.
- BOTTOM SIDE OF THE PCB IS CONTINUOUS GROUND PLANE.

- DENOTES PCB COPPER LAYOUT WITH SMOBC (SOLDER MASK OVER BARE COPPER).
- DENOTES COPPER LAND PATTERN FREE OF SOLDER MASK.

### OUTLINE DIMENSIONS (Inches/mm)

A	B	C	D	E	F
.079	.049	.033	.014	.012	.012
2.0	1.24	0.84	0.36	0.30	0.30
G	H	J	K	wt	
.026	.014	.039	.110	grams	
0.66	0.36	1.00	2.80	.008	

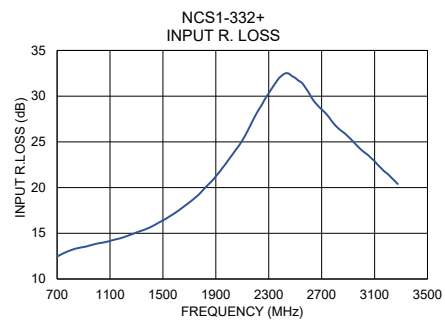
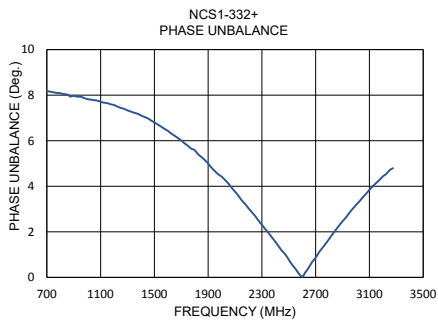
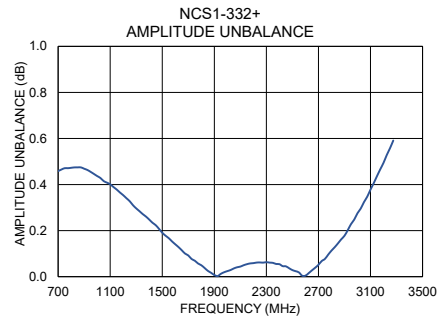
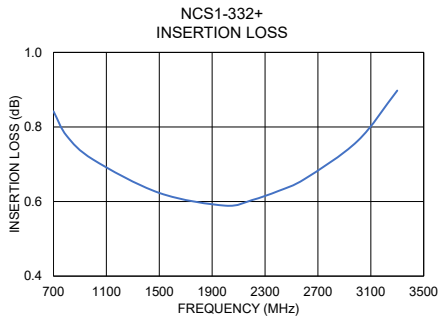
### TAPE & REEL INFORMATION: F74



### TYPICAL PERFORMANCE DATA<sup>3</sup>

Frequency (MHz)	Insertion Loss (dB)	Input Return Loss (dB)	Amplitude Unbalance (dB)	Phase Unbalance (deg)
700	0.84	12.45	0.46	8.18
800	0.78	13.13	0.47	8.09
1000	0.71	13.87	0.44	7.83
1500	0.62	16.41	0.19	6.80
2000	0.59	23.12	0.02	4.43
2200	0.60	27.91	0.06	3.04
2400	0.63	32.26	0.05	1.56
2600	0.66	30.44	0.00	0.03
3000	0.76	24.12	0.28	3.18
3300	0.90	20.03	0.63	4.92

3. Measured with Agilent E5071B network analyzer using impedance conversion and port extension.



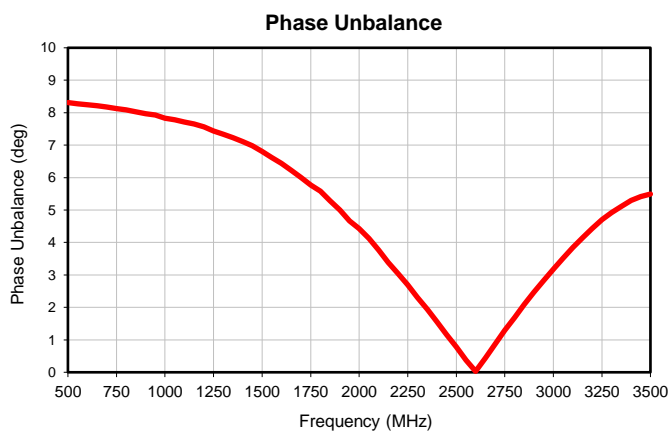
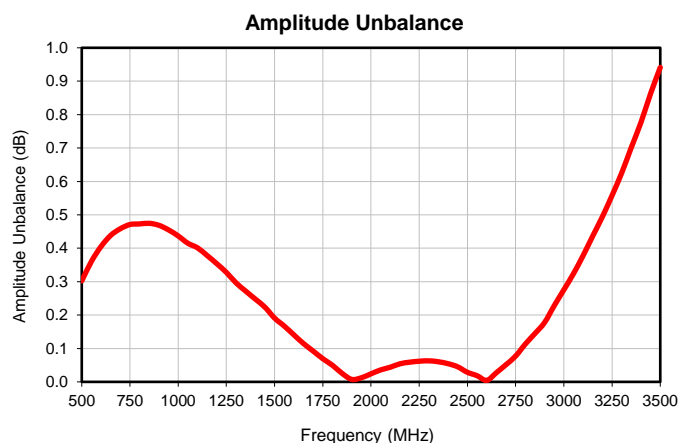
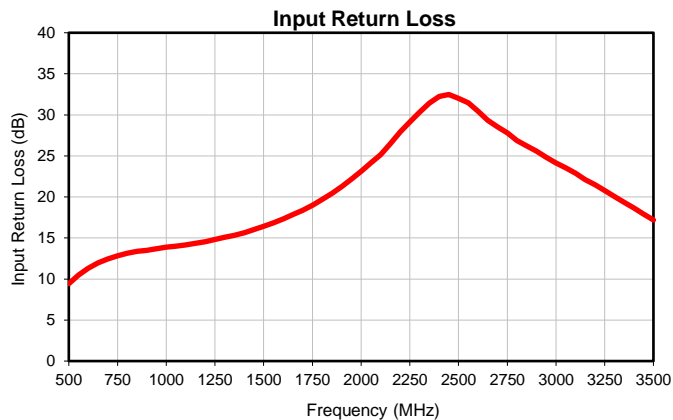
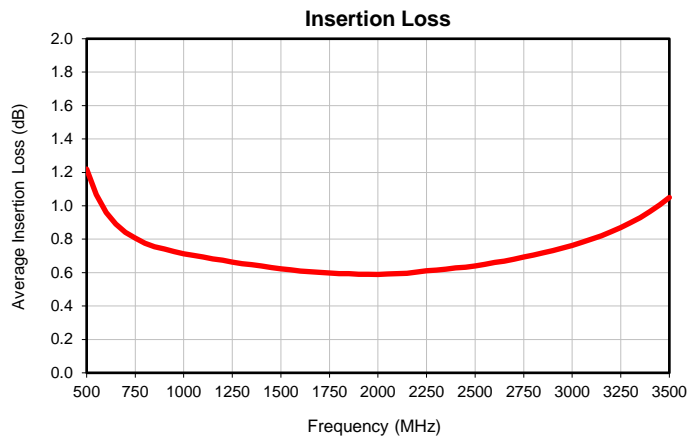
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  - B. Electrical specifications and performance data contained in this specification document are based on Mini-Circuit's applicable established test performance criteria and measurement instructions.
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## Typical Performance Data

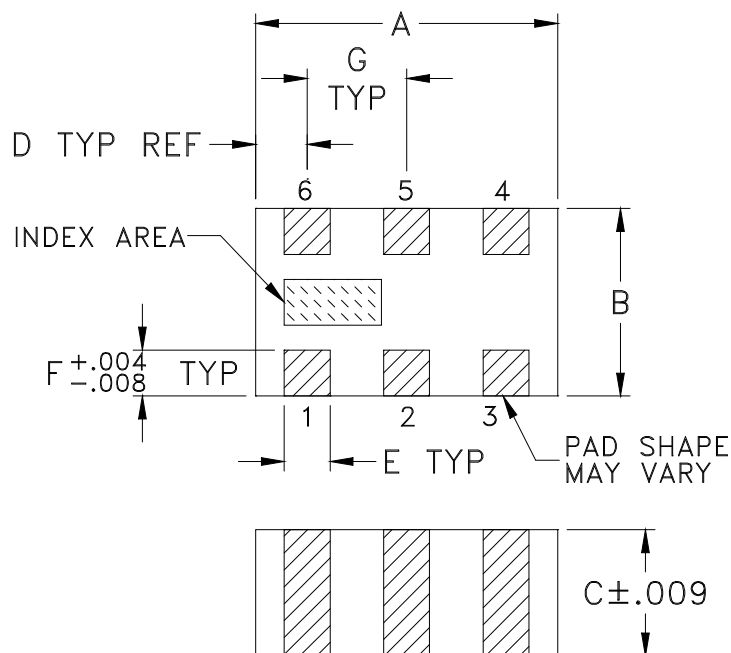
FREQUENCY (MHz)	INSERTION LOSS (dB)	INPUT RETURN LOSS (dB)	AMPLITUDE UNBALANCE (dB)	PHASE UNBALANCE <sup>(1)</sup> (Deg)
500	1.22	9.43	0.30	8.31
550	1.07	10.48	0.36	8.27
600	0.96	11.33	0.41	8.24
650	0.89	11.97	0.44	8.21
700	0.84	12.45	0.46	8.18
750	0.81	12.83	0.47	8.12
800	0.78	13.13	0.47	8.09
850	0.76	13.36	0.47	8.03
900	0.74	13.50	0.47	7.97
950	0.73	13.68	0.45	7.93
1000	0.71	13.87	0.44	7.83
1050	0.70	13.99	0.42	7.78
1100	0.69	14.17	0.40	7.71
1150	0.68	14.36	0.38	7.65
1200	0.67	14.56	0.35	7.56
1250	0.66	14.81	0.33	7.44
1300	0.65	15.09	0.30	7.33
1350	0.65	15.34	0.27	7.23
1400	0.64	15.64	0.25	7.11
1450	0.63	16.02	0.22	6.98
1500	0.62	16.41	0.19	6.80
1550	0.62	16.85	0.17	6.62
1600	0.61	17.31	0.14	6.44
1650	0.60	17.84	0.11	6.22
1700	0.60	18.38	0.09	6.01
1750	0.60	18.97	0.07	5.77
1800	0.59	19.68	0.05	5.59
1850	0.59	20.43	0.03	5.28
1900	0.59	21.23	0.01	5.00
1950	0.59	22.15	0.01	4.67
2000	0.59	23.12	0.02	4.43
2050	0.59	24.12	0.04	4.13
2100	0.59	25.16	0.04	3.76
2150	0.60	26.48	0.05	3.38
2200	0.60	27.91	0.06	3.04
2250	0.61	29.11	0.06	2.69
2300	0.62	30.31	0.06	2.31
2350	0.62	31.42	0.06	1.95
2400	0.63	32.26	0.05	1.56
2450	0.63	32.48	0.04	1.16
2500	0.64	32.01	0.03	0.78
2550	0.65	31.47	0.02	0.37
2600	0.66	30.44	0.00	0.03
2650	0.67	29.31	0.03	0.44
2700	0.68	28.54	0.05	0.87
2750	0.69	27.79	0.08	1.29
2800	0.70	26.86	0.11	1.69
2850	0.72	26.19	0.14	2.09
2900	0.73	25.58	0.18	2.47
2950	0.75	24.84	0.23	2.83
3000	0.76	24.12	0.28	3.18
3050	0.78	23.56	0.32	3.51
3100	0.80	22.89	0.38	3.84
3150	0.82	22.12	0.44	4.14
3200	0.84	21.48	0.49	4.43
3250	0.87	20.77	0.56	4.71
3300	0.90	20.03	0.63	4.92
3350	0.93	19.32	0.70	5.11
3400	0.97	18.62	0.78	5.29
3450	1.01	17.91	0.86	5.42
3500	1.05	17.21	0.94	5.49

<sup>(1)</sup> Relative to 180°

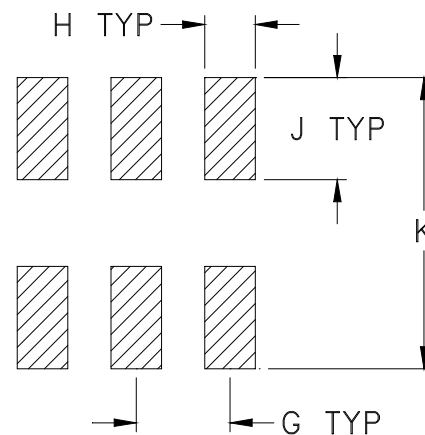
## Typical Performance Data



### Outline Dimensions



### PCB Land Pattern



Suggested Layout,  
Tolerance to be within  $\pm .002$

CASE #	A	B	C	D	E	F	G	H	J	K	WT.GRAM
GE0805C-9	.079 (2.00)	.049 (1.25)	.037 (0.95)	.014 (0.35)	.012 (0.30)	.012 (0.30)	.026 (0.65)	.014 (0.35)	.039 (1.00)	.110 (2.80)	.008

Dimensions are in inches (mm). Tolerances: 2Pl.  $\pm .01$ ; 3 Pl.  $\pm .005$

### Notes:

- Open style, ceramic base.
- Termination finish: For RoHS Case Styles: Tin plate over Nickel plate. All models, (+) suffix.  
For RoHS-5 Case Styles: Tin-Lead plate over Nickel plate. All models, no (+) suffix.



P.O. Box 350166, Brooklyn, New York 11235-0003 (718) 934-4500 Fax (718) 332-4661 For detailed performance specs & shopping online see Mini-Circuits web site



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RF/IF MICROWAVE COMPONENTS

# Tape & Reel Packaging TR-F114

## DEVICE ORIENTATION IN T&R



ILLUSTRATION 1

Applicable Case Styles	
GE0805C	JC0603C
GE0805C-1	JC0603C-4
GE0805C-1AP	JC0603C-6
GE0805C-7	
GE0805C-9	
GE0805C-10	
GE0805C-11	
GE0805C-12	



ILLUSTRATION 2

Applicable Case Styles	
GE0805C-2	JC0603C-1
GE0805C-3	JC0603C-2
GE0805C-4	JC0603C-3
GE0805C-5	JC0603C-5
GE0805C-6	JC0603C-7
GE0805C-8	
GE0805C-15	

Tape Width, mm	Device Cavity Pitch, mm	Reel Size, inches	Devices per Reel	
8	4	7	Small quantity standards (see note)	20
				50
				100
				200
				500
				1000
			Standard	4000

Note: Please Consult individual model data sheet to determine device per reel availability.

Mini-Circuits carrier tape materials provide protection from ESD (Electro-Static Discharge) during handling and transportation. Tapes are static dissipative and comply with industry standards EIA-481/EIA-541.

Go to: [www.minicircuits.com/pages/pdfs/tape.pdf](http://www.minicircuits.com/pages/pdfs/tape.pdf)



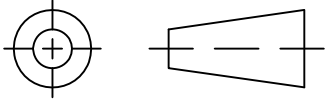
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THIRD ANGLE PROJECTION



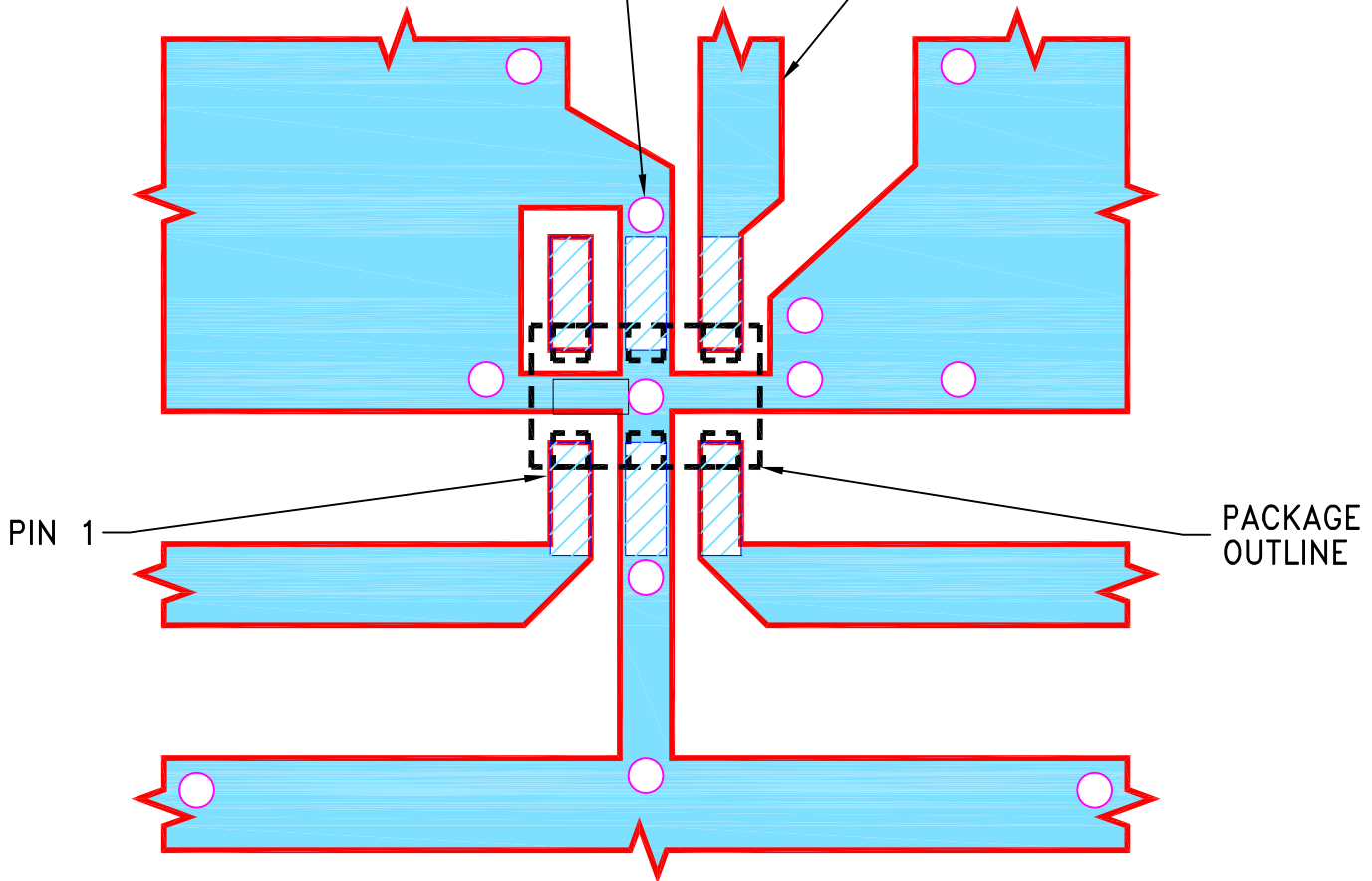
REVISIONS

REV	ECN No.	DESCRIPTION	DATE	DR	AUTH
OR	M167036	NEW RELEASE	03/27/18	ITG	BK

SUGGESTED MOUNTING CONFIGURATION  
FOR GE0805C-9 CASE STYLE, "06TR02" PIN CODE

∅.012 PTH FOR GROUND, PLUGGED FROM TOP SIDE & CAPPED WITH COPPER ON TOP & BOTTOM SIDES.

.028 TRACE WIDTH & .046 GAP, 3 PL.

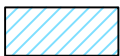


NOTES:

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- BOTTOM SIDE OF THE PCB IS CONTINUOUS GROUND PLANE.



DENOTES PCB COPPER LAYOUT WITH SMOBC (SOLDER MASK OVER BARE COPPER).



DENOTES COPPER LAND PATTERN FREE OF SOLDER MASK.

UNLESS OTHERWISE SPECIFIED	INITIALS	DATE
DIMENSIONS ARE IN INCHES	DRAWN ITG	03/26/18
TOLERANCES ON:	CHECKED GF	03/27/18
2 PL DECIMALS ±	APPROVED BK	03/27/18
3 PL DECIMALS ± .005		
ANGLES ±		
FRACTIONS ±		



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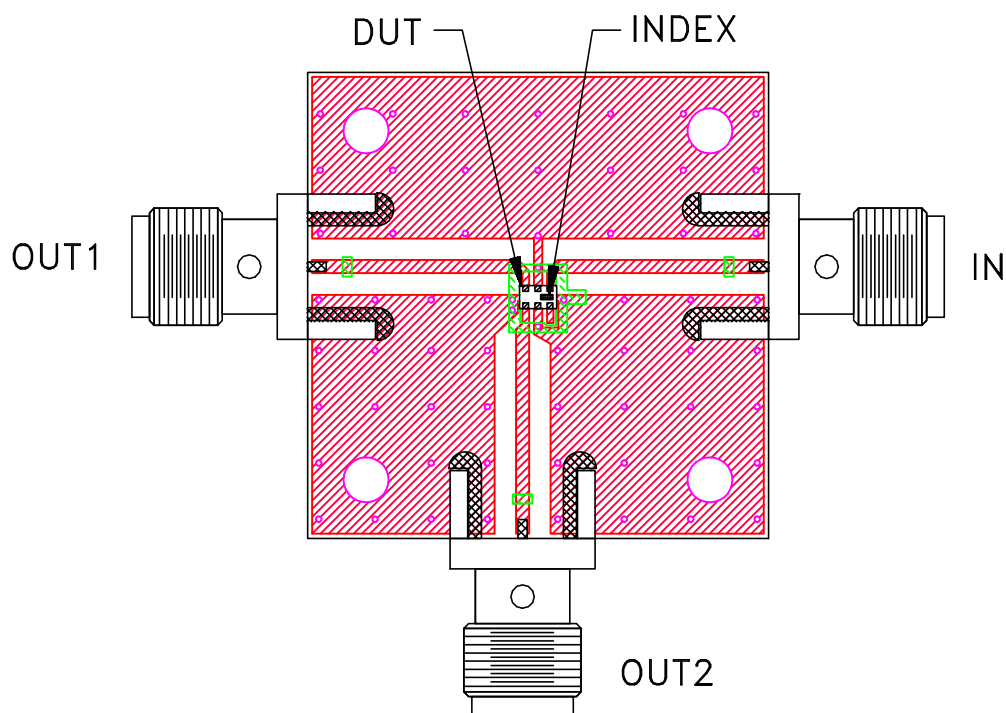
13 Neptune Avenue  
Brooklyn NY 11235

PL, 06TR02, GE0805C-9, TB-910+

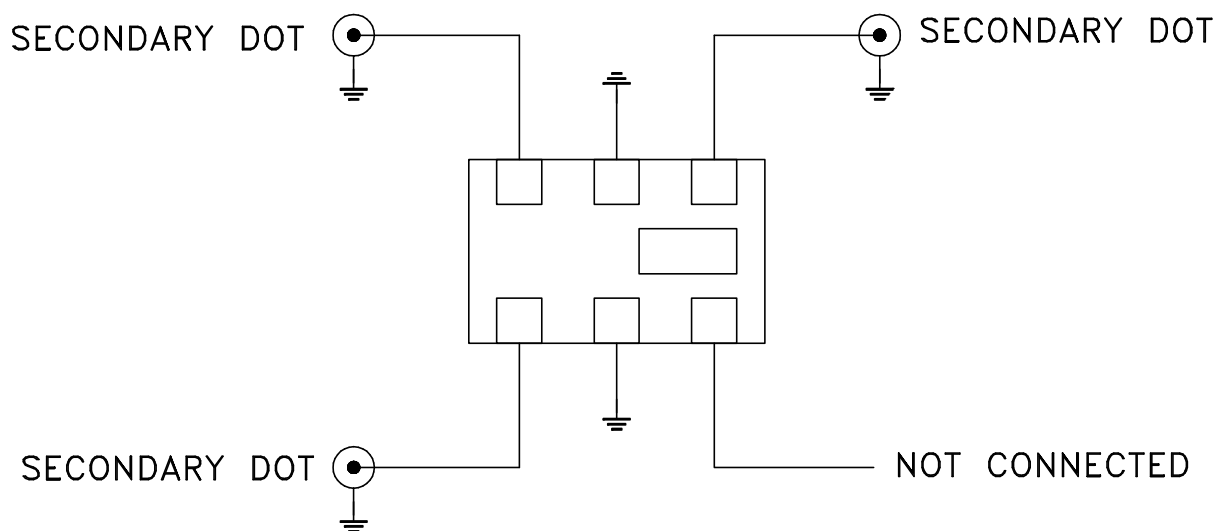
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SIZE A	CODE IDENT 15542	DRAWING NO: 98-PL-583	REV: OR
FILE: 98PL583	SCALE: 15:1	SHEET: 1 OF 1	

# Evaluation Board and Circuit




TB-910-332+



Schematic Diagram

## Notes:

1. 50 Ohm SMA Female connectors.
2. PCB Material: FR4 or equivalent,  
Dielectric Constant=4.6,  
Thickness=.016 inch.

 **Mini-Circuits®**

All Mini-Circuits products are manufactured under exacting quality assurance and control standards, and are capable of meeting published specifications after being subjected to any or all of the following physical and environmental test.

Specification	Test/Inspection Condition	Reference/Spec
Operating Temperature	-55° to 100°C Ambient Environment	Individual Model Data Sheet
Storage Temperature	-55° to 100° C Ambient Environment	Individual Model Data Sheet
Humidity	90 to 95% RH, 240 hours, 50°C	MIL-STD-202, Method 103, Condition A, Except 50°C and end-point electrical test done within 12 hours
Solder Reflow Heat	Sn-Pb Eutetic Process: 225°C peak Pb-Free Process 245° - 250°C peak	J-STD-020, Table 4-1, 4-2 and 5-2, Figure 5-1
Solderability	10X Magnification	J-STD-002, Para 4.2.5, Test S, 95% Coverage
Vibration (High Frequency)	20g peak, 10-2000 Hz, 12 times in each of three perpendicular directions (total 36)	MIL-STD-202, Method 204, Condition D
Mechanical Shock	50g, 11 ms, 1/2-sine, 18 shocks: 3 each direction, each of 3 axes	MIL-STD-202, Method 213, Condition A